# Photovoltaic cell and module physics and technology

Vitezslav Benda, Prof Czech Technical University in Prague

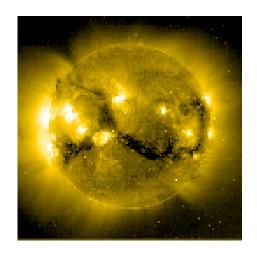
benda@fel.cvut.cz

www.fel.cvut.cz

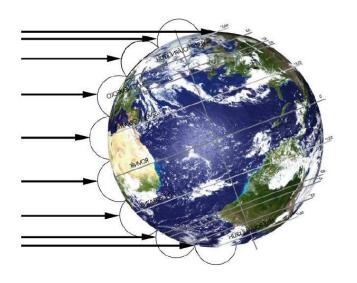
# **Outlines**

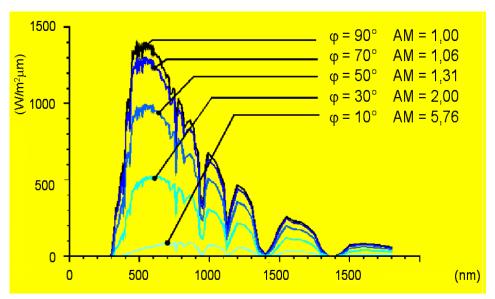
- Photovoltaic Effect
- Photovoltaic cell structure and characteristics
- Photovoltaic cell construction and technology
- PV modules construction and technology
- Summary

# Solar energy









#### **Photovoltaics**

Direct transformation energy of solar irradiation into electricity

# 1. Light absorption in materials and excess carrier generation

Photon energy  $h v = hc/\lambda$  (h is the Planck constant) photon momentum  $\approx 0$ 

Light is absorbed in the material.

$$\Phi(x)$$
 is the light intensity  $\Phi(x) = \Phi_0 \exp(-\alpha x) = \Phi_0 \exp\left(-\frac{x}{x_L}\right)$ 
 $\alpha = \alpha(\lambda)$  is the absorption coefficient
 $x_L = \frac{1}{\alpha}$  is the so-called **absorption length**

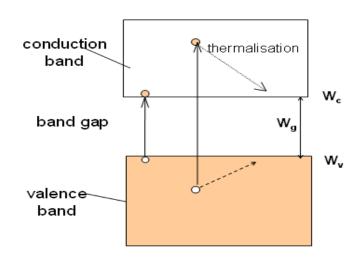
$$\int_0^{x_L} \Phi(x) dx = 0.68 \int_0^{\infty} \Phi(x) dx$$

Absorption is due to interactions with material particles (electrons and nucleus). If particle energy before interaction was  $W_1$ , after photon absorption is  $W_1 + h v$ 

- interactions with the lattice –results in an increase of temperature
- interactions with free electrons results also in temperature increase
- interactions with bonded electrons- the incident light may generate some excess carriers (electron/hole pairs)

At interaction with photons of energy  $h_{\mathcal{V}} \ge W_g$  are generated and carrier generation increases

electron-hole pairs



$$G(\lambda; x) = \left(\frac{d\Delta n}{dt}\right)_{gen} = \alpha(\lambda)\beta(\lambda)\Phi_0(\lambda)\exp\left(-\alpha(\lambda)x\right)$$

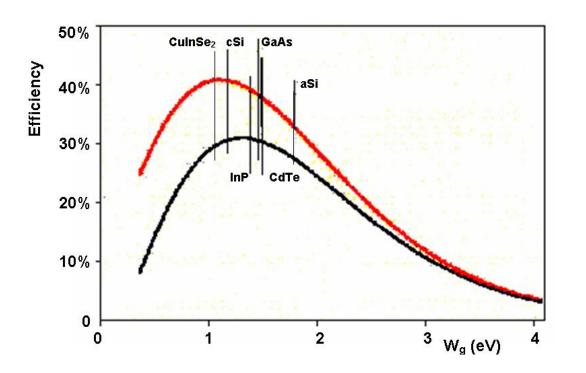
$$n = n_0 + \Delta n$$
,  $p = p_0 + \Delta p$ 

Excess carriers recombine with the recombination rate  $\tau$  is so called carrier lifetime

$$R = \left(\frac{d\Delta n}{dt}\right)_{rec} = -\frac{\Delta n}{\tau}$$

In dynamic equilibrium  $\Delta n = \Delta p = \tau G$ 

# Efficiency of excess carrier generation by solar energy depens on the semiconductor band gap



### Suitable materials

Silicon
GaAs
CuInSe<sub>2</sub>
amorphous SiGe
CdTe/CdS

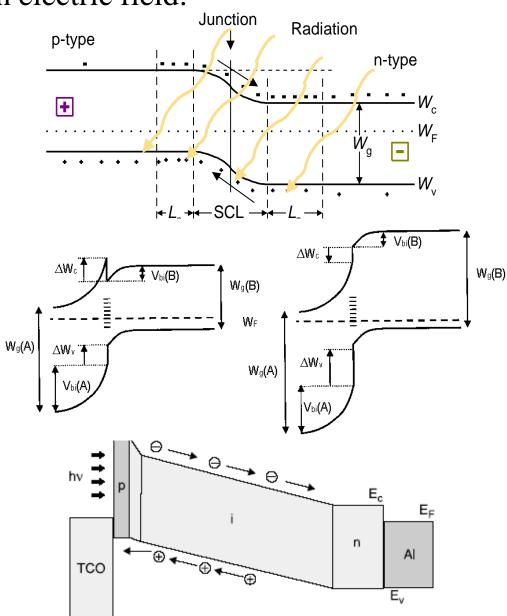
To obtain a potential difference that may be used as a source of electrical energy, an inhomogeneous structure with internal electric field is necessary.

#### Suitable structures with built-in electric field:

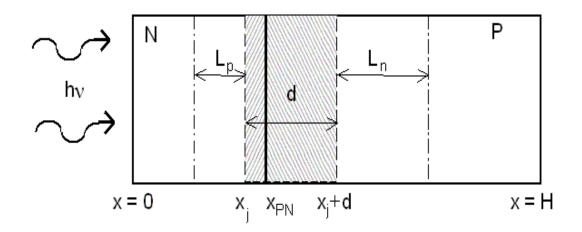
PN junction

• heterojunction (contact of different materials).

• PIN structures



# Principles of solar cell function



In the illuminated area generated excess carriers diffuse towards the PN junction. The density  $J_{PV}$  is created by carriers collected by the built-in electric field region

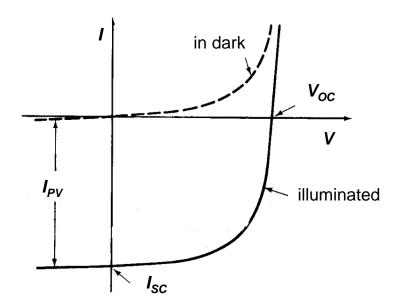
$$J_{PV}(\lambda) = q \int_{0}^{H} G(\lambda; x) dx - q \int_{0}^{H} \frac{\Delta n}{\tau} dx - J_{sr}(0) - J_{sr}(H)$$

$$J_{sr} \text{ is surface recombination}$$

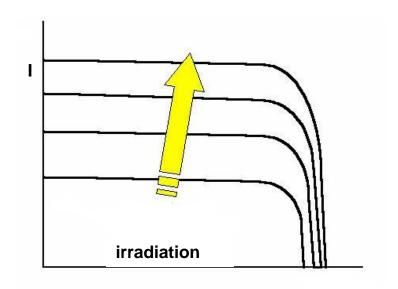
Total generated current density

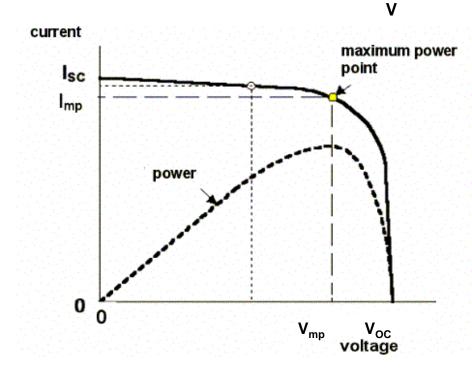
$$J_{PV} = \int J_{PV}(\lambda) d\lambda$$

Illuminated PN junction: supperposition of photo-generated current and PN junction (dark) I-V characteristic

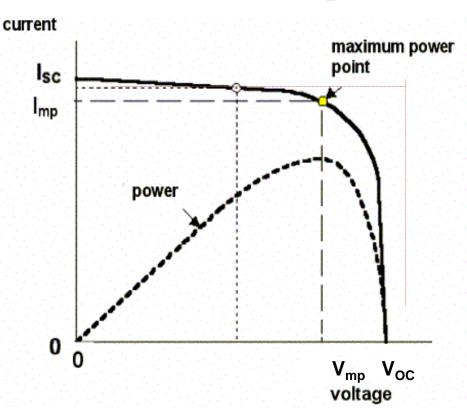


Solar cell I-V chacteristic and its importan points





# Important solar cell electrical parameters



- open circuit voltage  $V_{OC}$ ,
- short circuit current  $I_{SC}$
- maximum output power  $V_{mp}I_{mp}$

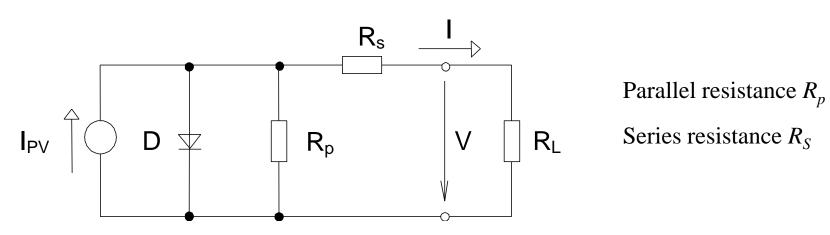
• fill factor 
$$FF = \frac{V_{mp}I_{mp}}{V_{OC}I_{SC}}$$

• efficiency 
$$\eta = \frac{V_{mp}I_{mp}}{P_{in}} = \frac{V_{OC}I_{SC}FF}{P_{in}}$$

All parameters  $V_{OC}$ ,  $I_{SC}$ ,  $V_{mp}$ ,  $I_{mp}$ , FF and  $\eta$  are usually given for standard testing conditions (STC):

- spectrum AM 1.5
- radiation power 1000 W/m<sup>2</sup>
- cell temperature 25°C.

# Modelling I-V characteristics of a solar cell



PN junction I-V characteristics

$$J = J_{01} \left[ \exp \left( \frac{qV_j}{\varsigma_1 kT} \right) - 1 \right] + J_{02} \left[ \exp \left( \frac{qV_j}{\varsigma_2 kT} \right) - 1 \right]$$

$$J_{01} = n_{\rm i}^2 q \left( \frac{D_{\rm n}}{L_{\rm n}} \frac{1}{p_{\rm p0}} + \frac{D_{\rm p}}{L_{\rm p}} \frac{1}{n_{\rm n0}} \right) \qquad J_{02} = \frac{q n_i d}{\tau_{\rm sc}} \qquad 1 \le \zeta_1 \le 2 \qquad 2 \le \zeta_2$$

Output cell voltage  $V = V_i - R_s I$ 

A - total cell area A<sub>ill</sub> - illuminated cell area

$$I = A_{ill}J_{PV} - AJ_{01} \left[ \exp \left( q \frac{V + R_s I}{\varsigma_1 kT} \right) - 1 \right] - AJ_{02} \left[ \exp \left( q \frac{V + R_s I}{\varsigma_2 kT} \right) - 1 \right] - \frac{V + R_s I}{R_p}$$

# **Influence of temperature**

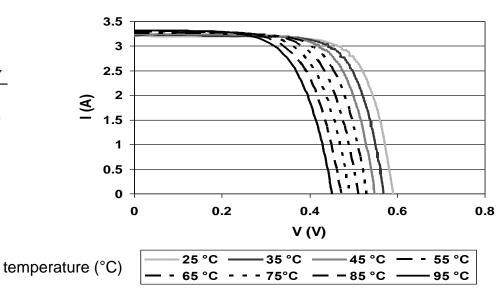
For a high R<sub>p</sub> 
$$V_{OC} \approx \frac{kT}{q} \ln \frac{I_{PV}}{I_{01}}$$
 
$$I_{01} \sim n_i^2 = BT^3 \exp \left(\frac{-W_g}{kT}\right)$$
 Consequently 
$$\frac{\partial V_{OC}}{\partial T} < 0$$

For silicon cells the decrease of  $V_{OC}$  is about 0.4%/K

Both fill factor and efficiency decrease with temperature

$$\frac{\partial FF}{\partial T} < 0 \qquad \frac{\partial \eta}{\partial T} < 0$$

At silicon cells  $\frac{1}{\eta} \frac{\partial \eta}{\partial T} \approx 0.5\% K^{-1}$ 

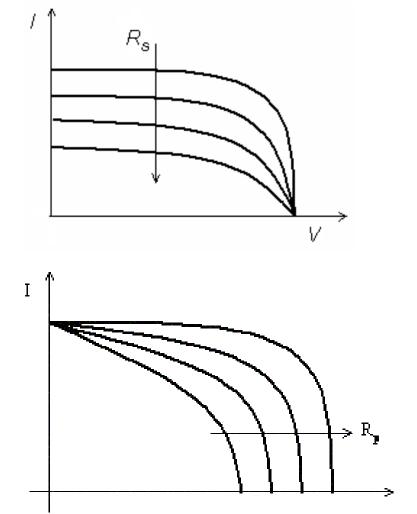


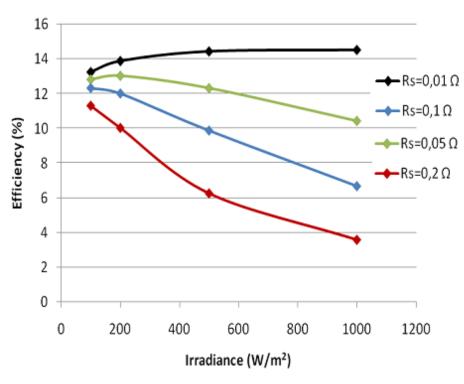
 $R_s$  increases with increasing temperature  $R_p$  decreases with increasing temperature

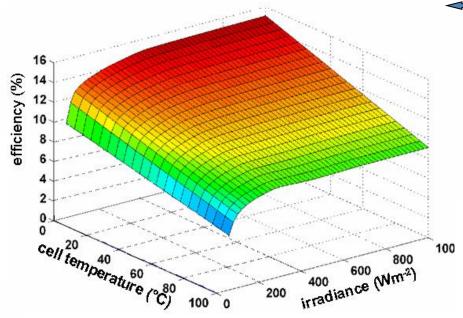
Cell type	η (28°C)	$(1/\eta)(d\eta/dT)$ [×10 <sup>-3</sup> /°C]
Si	0.148	-4.60
Ge	0.090	-10.1
GaAs/Ge	0.174	-1.60
InP	0.195	-1.59
a-Si	0.066	-1.11 (nonlinear)
CuInSe <sub>2</sub>	0.087	-6.52

# The resistances $R_{\rm s}$ and $R_{\rm p}$ influences the cell efficiency

#### At a constant irradiance



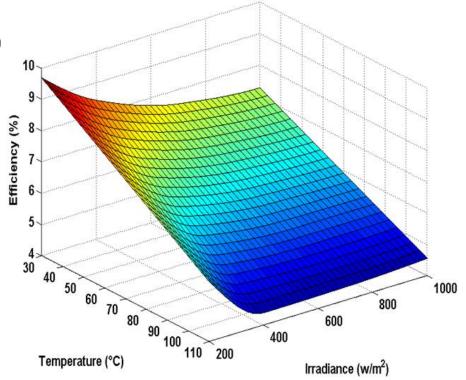




PV cell (module) with a high  $R_s$ 

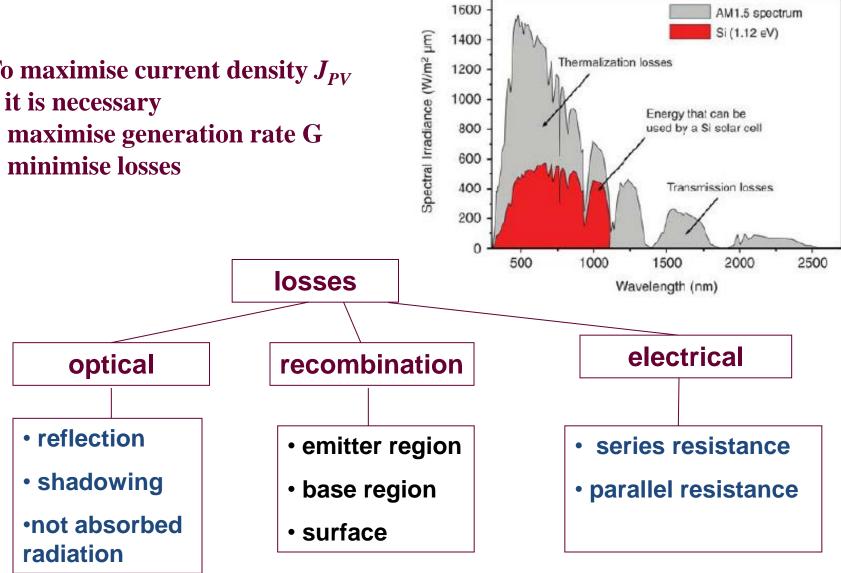
The efficiency decreases with increasing irradiance

PV cell (module) with a low R<sub>s</sub>
the efficiency increases with irradiance



# To maximise current density $J_{PV}$ it is necessary

- minimise losses

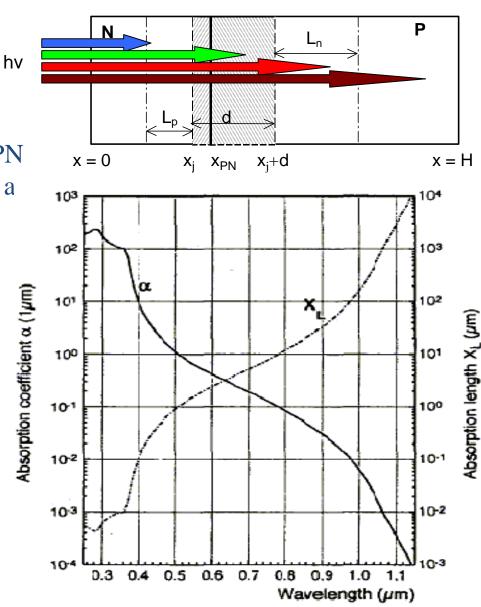


# Optimising cell thickness and PN junction depth

The photo-current density  $J_{PV}$  consists from carriers collected by the electric field in the space charge region of the PN junction, i.e. from carriers generated in a distance of about diffusion length from the PN junction.

The PN junction depth  $x_j$  should be less than 0.5  $\mu$ m (0.2  $\mu$ m is desirable).

To decrease recombination, defects should be passivated



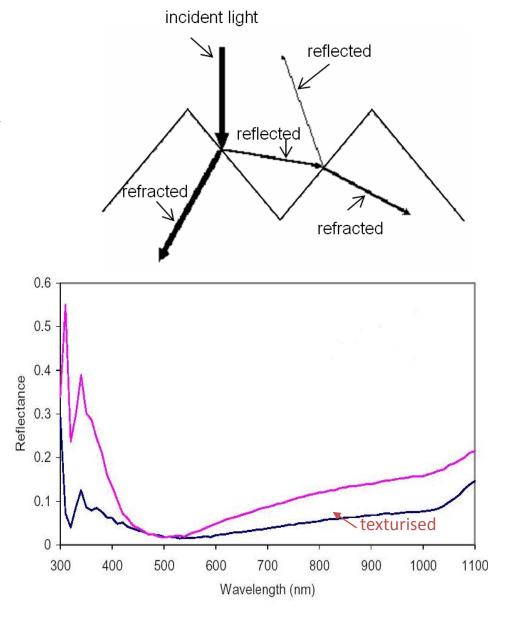
# **Optical losses**

# Surface texturing

If the surface has a pyramidal structure it is possible to decrease reflection on about one third of that on a plane surface

# Antireflection coating

Both principles (surface texturing and antireflection coating) can be combined to minimise losses by surface reflection

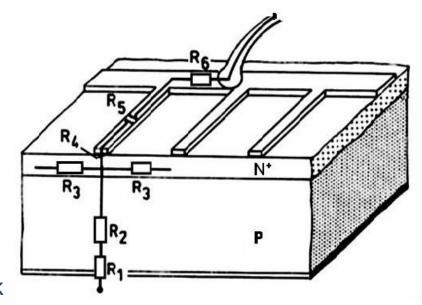


# Electrical losses

Series resistance R<sub>s</sub> influences strongly solar cells efficiency

# Series resistance $R_s$ consists of:

- •R<sub>1</sub> contact metal-semiconductor on the back surface
- •R<sub>2</sub> base semiconductor material
- •R<sub>3</sub> lateral emitter resistance between two contact grid fingers
- •R<sub>4</sub> contact metal-semiconductor on the grid fingers
- •R<sub>5</sub> resistance of the grid finger
- •R<sub>6</sub> resistance of the collector bus



$$R_2 = \rho_{Si} H / A$$

$$R_3 \sim \frac{\rho_N d}{x_i}$$

$$R_5 = \frac{\rho_M l}{3bh}$$

$$R_6 \sim \frac{\rho_M l_B}{h b_B}$$

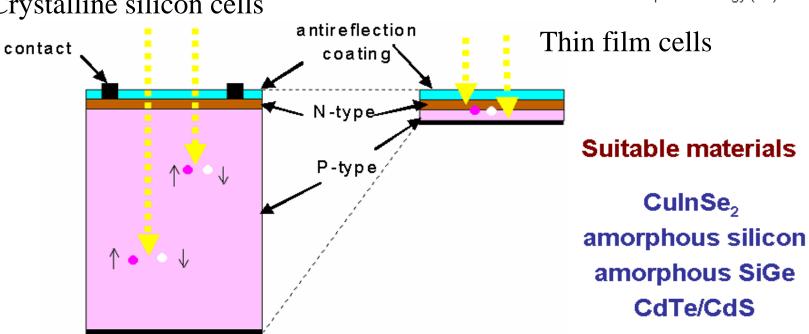
Two types of band structure

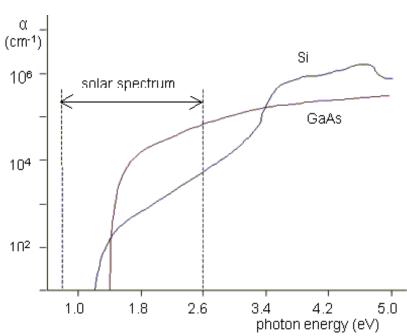
-direct (GaAs like)

-undirect (Si like)

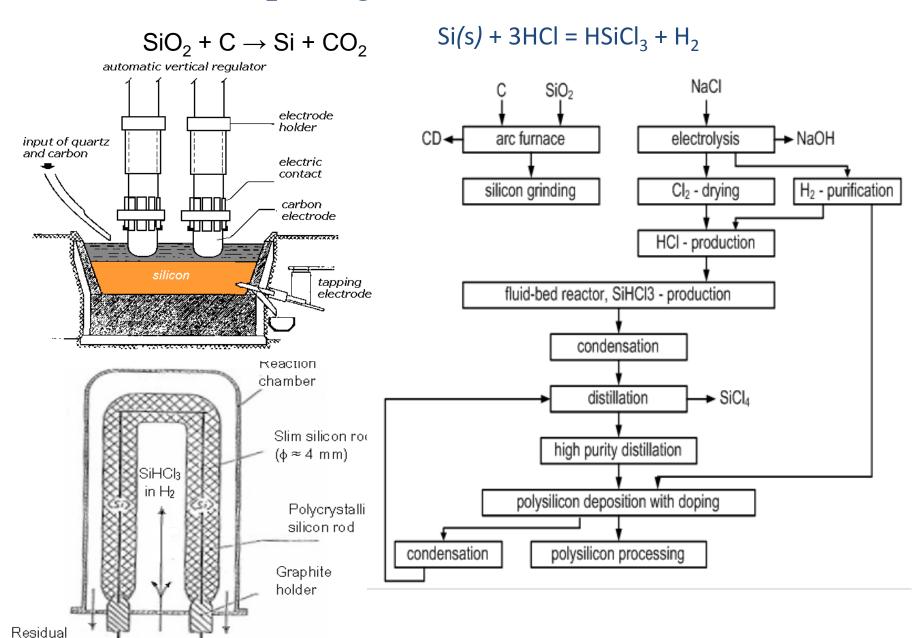
### **Basic types of solar cells:**

Crystalline silicon cells





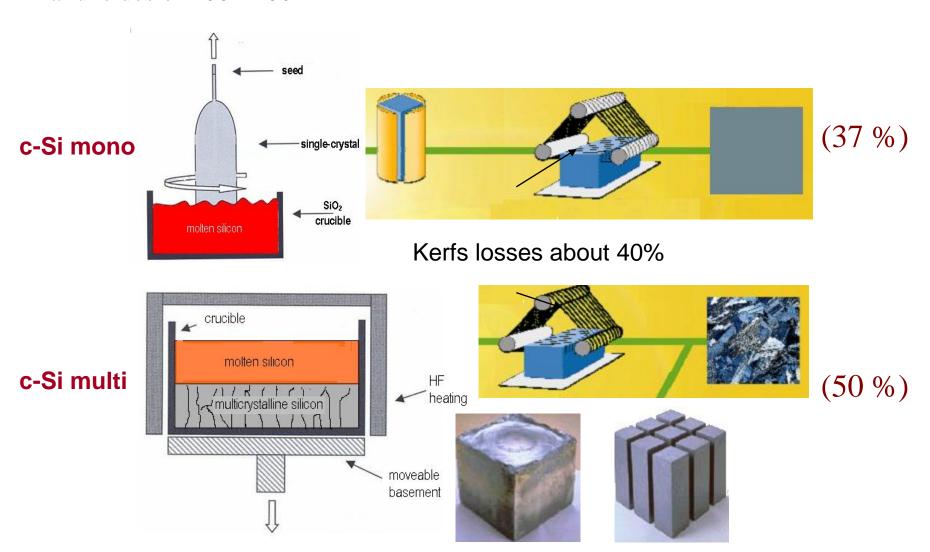
# Preparing semicondutor silicon



gases

# PV cells and modules from crystalline silicon (c-Si)

PV cells are realised from crystalline silicon wafers of thickness 0.15 - 0.25 mm and sides of 100 - 200 mm

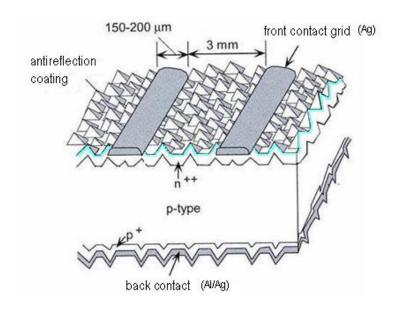


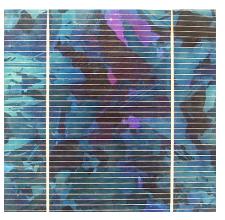
# Standard mass production (c-Si cells)

- starting P-type wafers
- chemical surface texturing
- phosphorous diffusion
- SiN(H) antireflection surface coating and passivation
- contact grid realised by the screen print technique
- contact firing
- edge grinding
- cell measuring and sorting



mono-crystalline  $\eta \approx 17\%$ 





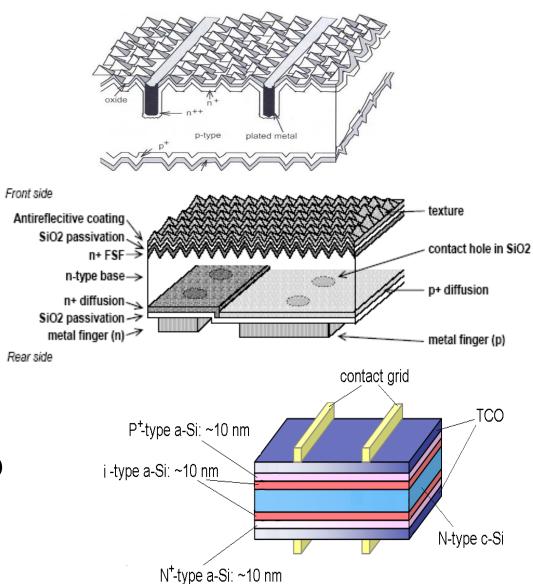
multi-crystalline  $\eta \approx 16\%$ 

### Increasing cell efficiency

Selective emitter

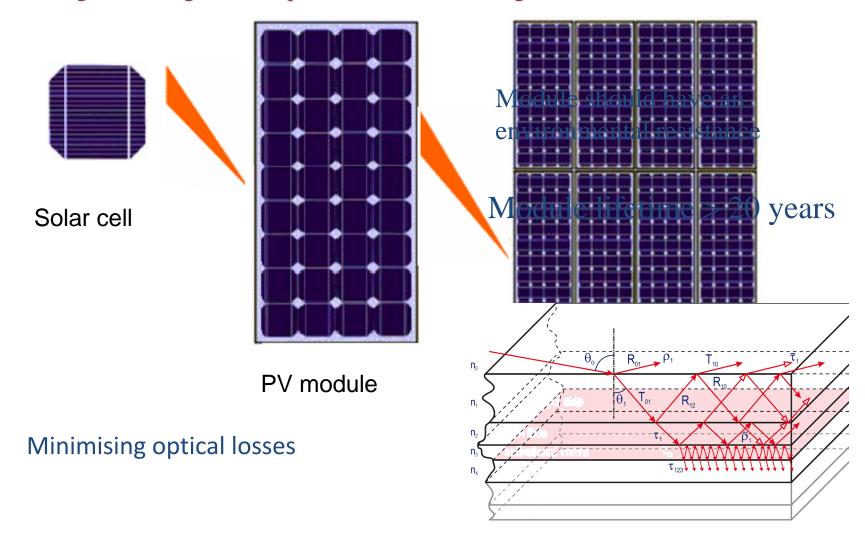
Back contact cells

Hetero junction cells (HIT)

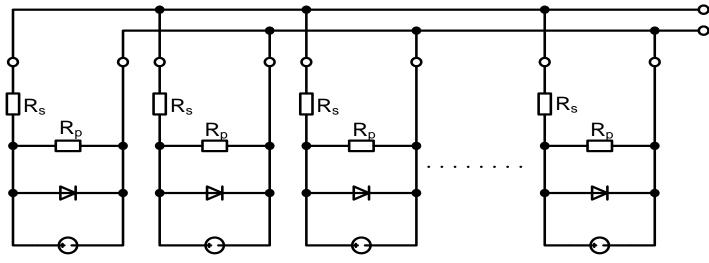


#### A single solar cell.....~0.5 V, about 30 mA/cm<sup>2</sup>

For practical use it is necessary connect cells in series to obtain a source of higher voltage and in parallel to obtain a higher current

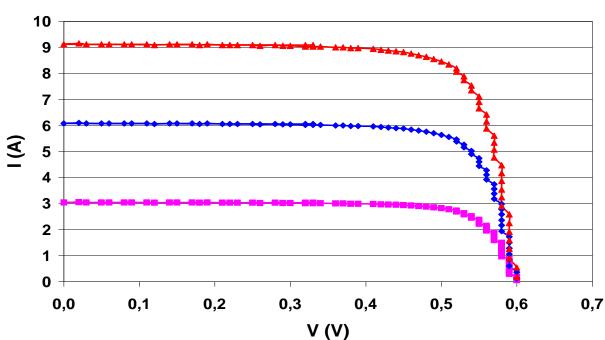


# **Cell connection in parallel**

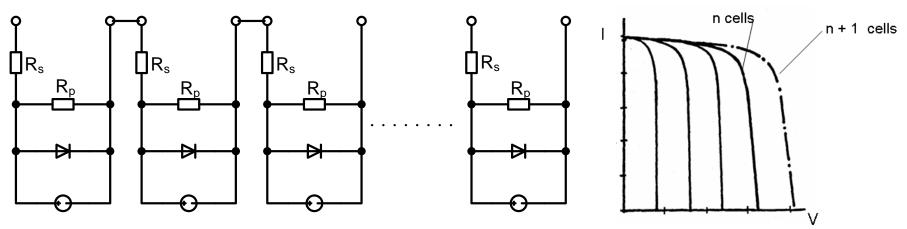


Optimum situation: all cells have the same  $V_{MP}$ 

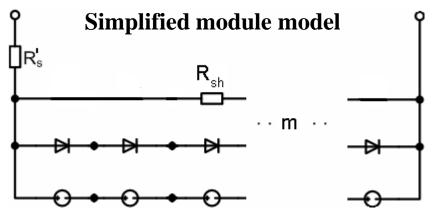
If characteristics of individual cells in parallel differ, efficiency decreases



# Cells in series..... the same current flows through all cells voltage does sums



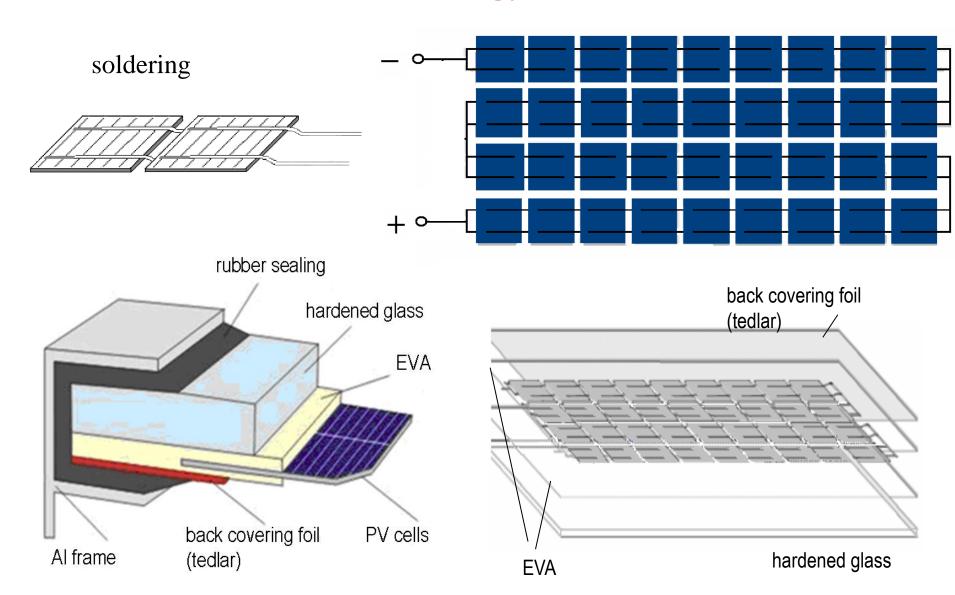
# Optimum situation: all cells have the same $I_{MP}$



If characteristics of individual cells in series differ, efficiency decreases

$$I = I_{PV} - I_{01} \left[ \exp \left( q \frac{V + R_{s}'I}{m\varsigma_{1}kT} \right) - 1 \right] - I_{02} \left[ \exp \left( q \frac{V + R_{s}'I}{m\varsigma_{2}kT} \right) - 1 \right] - \frac{V + R_{s}'I}{R_{sh}}$$

# PV c-Si module technology



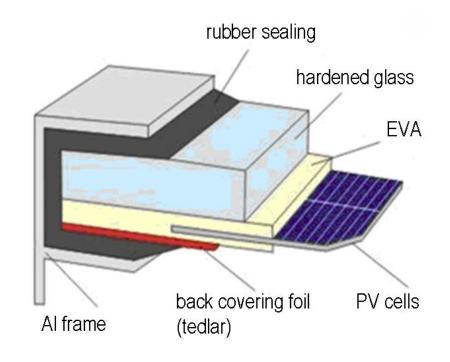
#### Module parameters

- open circuit voltage  $V_{OC}$ ,
- short circuit current  $I_{SC}$
- maximum output power  $V_{mp}I_{mp}$

• fill factor 
$$FF = \frac{V_{mp}I_{mp}}{V_{OC}I_{SC}}$$

• efficiency 
$$\eta = \frac{V_{mp}I_{mp}}{P_{in}} = \frac{V_{OC}I_{SC}FF}{P_{in}}$$

STC (25°C, 1kW/m<sup>2</sup>, AM 1,5)



 $T_c = T_a + r_{thea}G_{ab}$ 

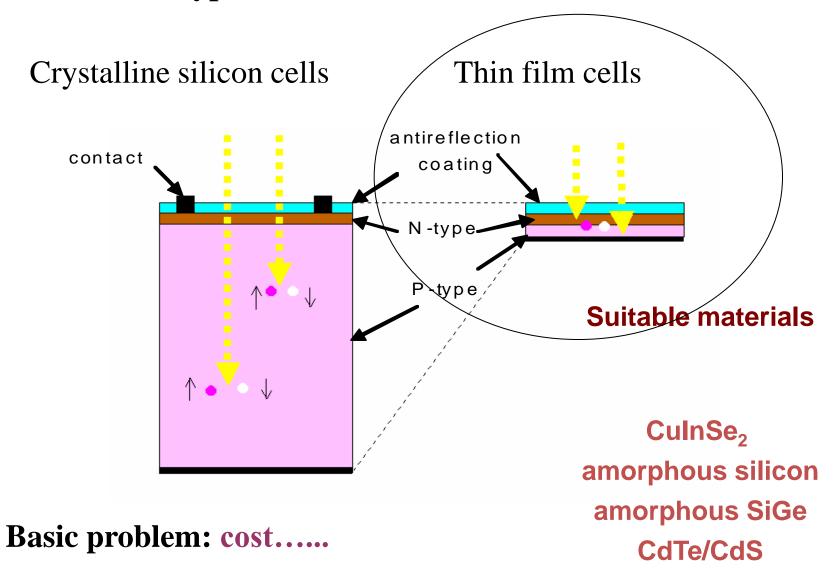
#### Real operating temperature

$$r_{\text{thca}} = \frac{r_{\text{thcaf}} r_{\text{thcab}}}{r_{\text{thcaf}} + r_{\text{thcab}}} \qquad r_{\text{thcab}} = \frac{d_b}{\lambda_b} + \frac{1}{h_b} \qquad r_{\text{thcaf}} = \frac{d_f}{\lambda_f} + \frac{1}{h_f}$$

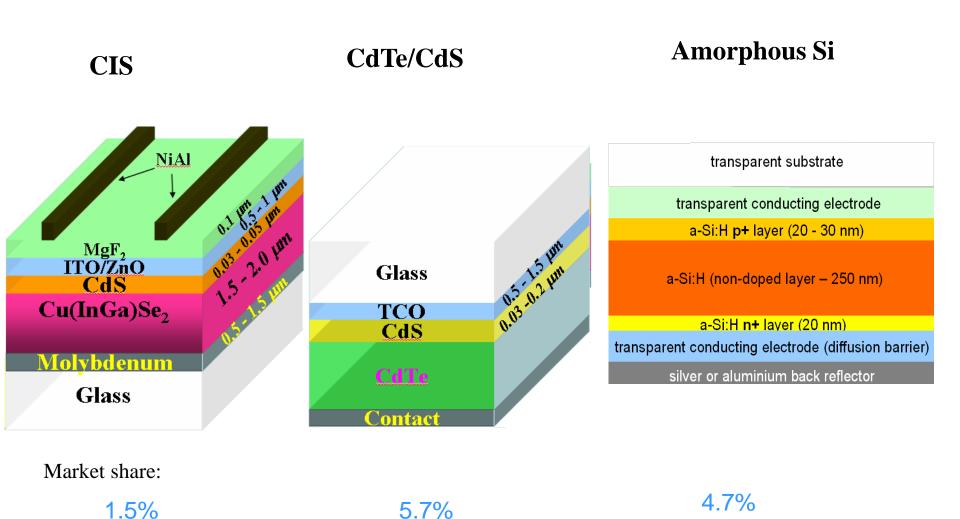
**NOCT** (Nominal Operating Conditions Temperature)

Ambient temperature 20°C, 800 W/m<sup>2</sup>, wind 1 m/s

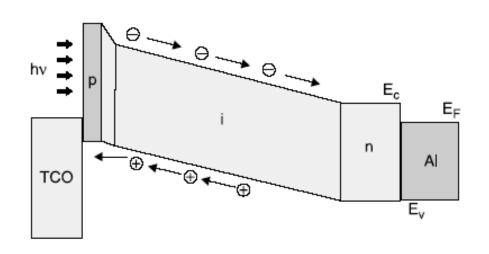
# **Basic types of solar cells:**

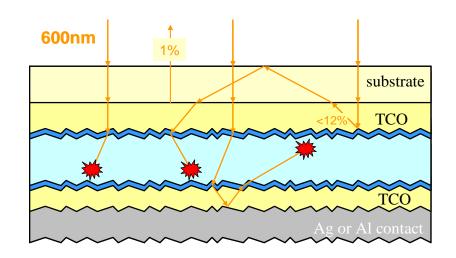


#### Thin film solar cells



# Amorphous silicon solar cells



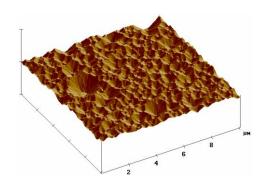


# TCO:

 $SnO_2$ 

ITO (indium-tin oxide)

ZnO

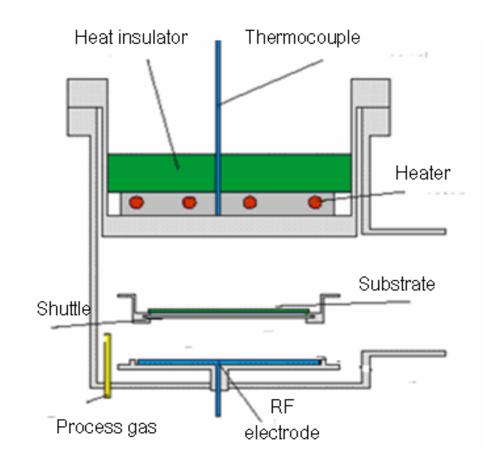


Light trapping

# Plasma enhanced CVD (PECVD)

RF electrode and substrate create the capacitor structure.

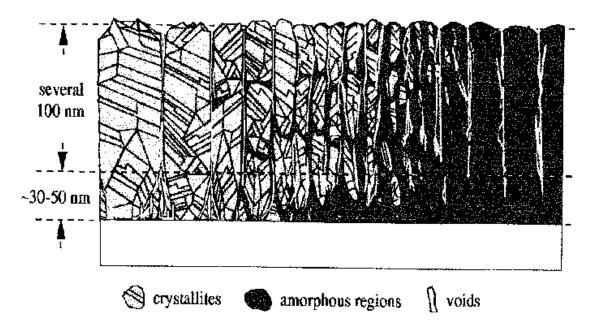
In this space the plasma and incorporated deposition of material on substrate takes place



deposition of silicon nitride  $3SiH_4 + 3NH_3 \rightarrow Si_3N_4 + 12H_2$  deposition polysilicon layers  $SiH_4 \rightarrow Si + 2H_2$ .

The deposited layer structure depends on the gas composition and substrate temperature

150 - 350°C



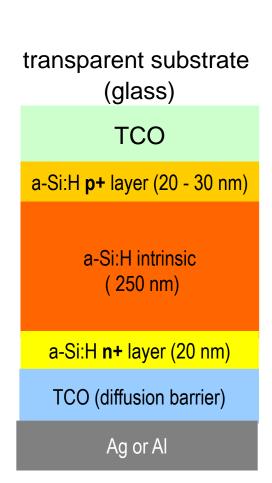
dilution ratio  

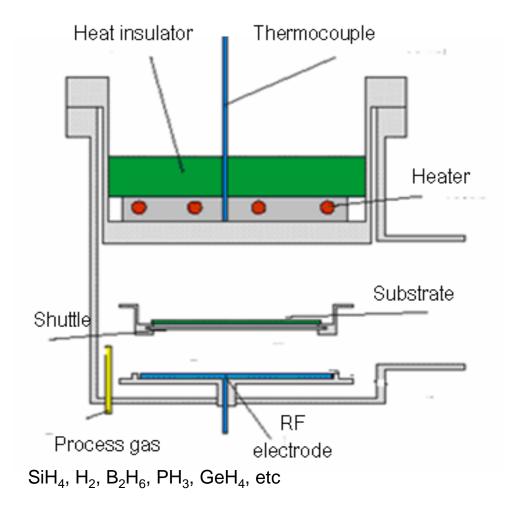
$$rH = ([H2] + [SiH4])/[SiH4].$$

rH < 30, amorphous silicon growth rH > 45, crystalline layers are formed

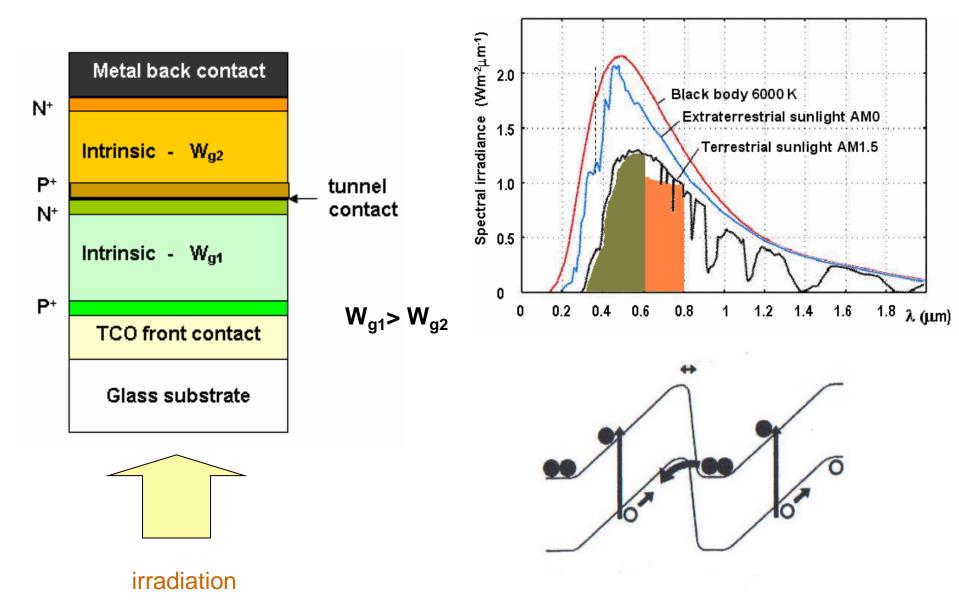
# Thin film solar cell technology

# Amorphous (microcrystalline) silicon solar cells





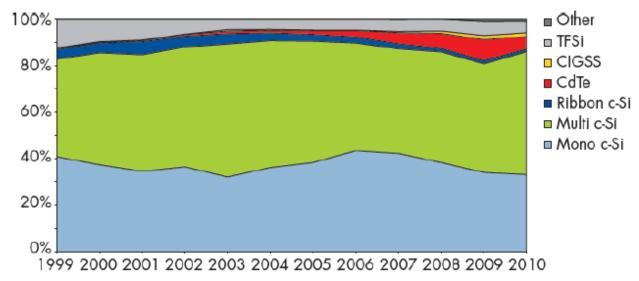
# **Tandem cells**



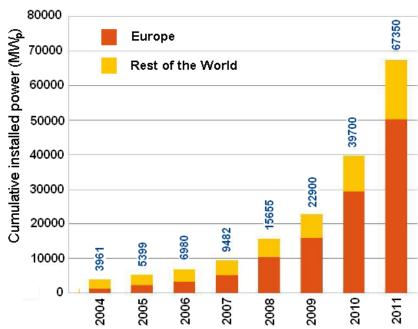
# Thin film modules on glass substrates

The module area is limited by the reaction Heat insulator Thermocouple chamber volume Heater Substrate Shuttle Cell n+2 Cell n+1 RF Process gas electrode Laser Scribing #3 Very expensive equipment Laser Scribing #2 Metal Coated Curibbon Silver filled adhesive a-Si Laser Scribing #1 TF-Si substrate TCO Back contact Glass

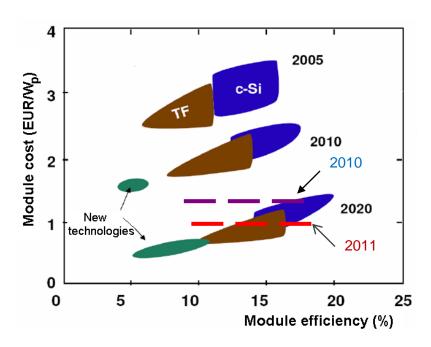
# Market share development



2010 2011
Crystalline silicon 84,4% 87%
Thin Film 14,8% 12%
Others 0,9% 1%



# PV module cost development



Reduction of C-Si module cost

Thin-film modules are not cheaper than modules from crystalline silicon

#### Reduction of silicon cost

2008..... 500 USD/kg2010......55 USD/kg2012...... 22 USD/kg

